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(12) **United States Design Patent** (10) **Patent No.:** **US D935,424 S**  
**Juco** (45) **Date of Patent:** **\*\* Nov. 9, 2021**

- (54) **SEMICONDUCTOR WAFER PROCESSING TOOL**
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- (73) Assignee: **Lam Research Corporation**, Fremont, CA (US)

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(\*\*) Term: **15 Years**

(21) Appl. No.: **29/690,193**

(22) Filed: **May 6, 2019**

(51) **LOC (13) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182; D10/46**

(58) **Field of Classification Search**  
USPC ..... D3/30, 200, 201, 212, 217, 283,  
D3/308-310, 326; D8/349; D9/414, 430,  
D9/456, 499; D10/46, 75, 77, 78, 81,  
D10/102; D13/182; D15/140  
CPC ..... H01L 21/561; H01L 21/78; H01L 24/11;  
H01L 24/96; H01L 24/97  
See application file for complete search history.

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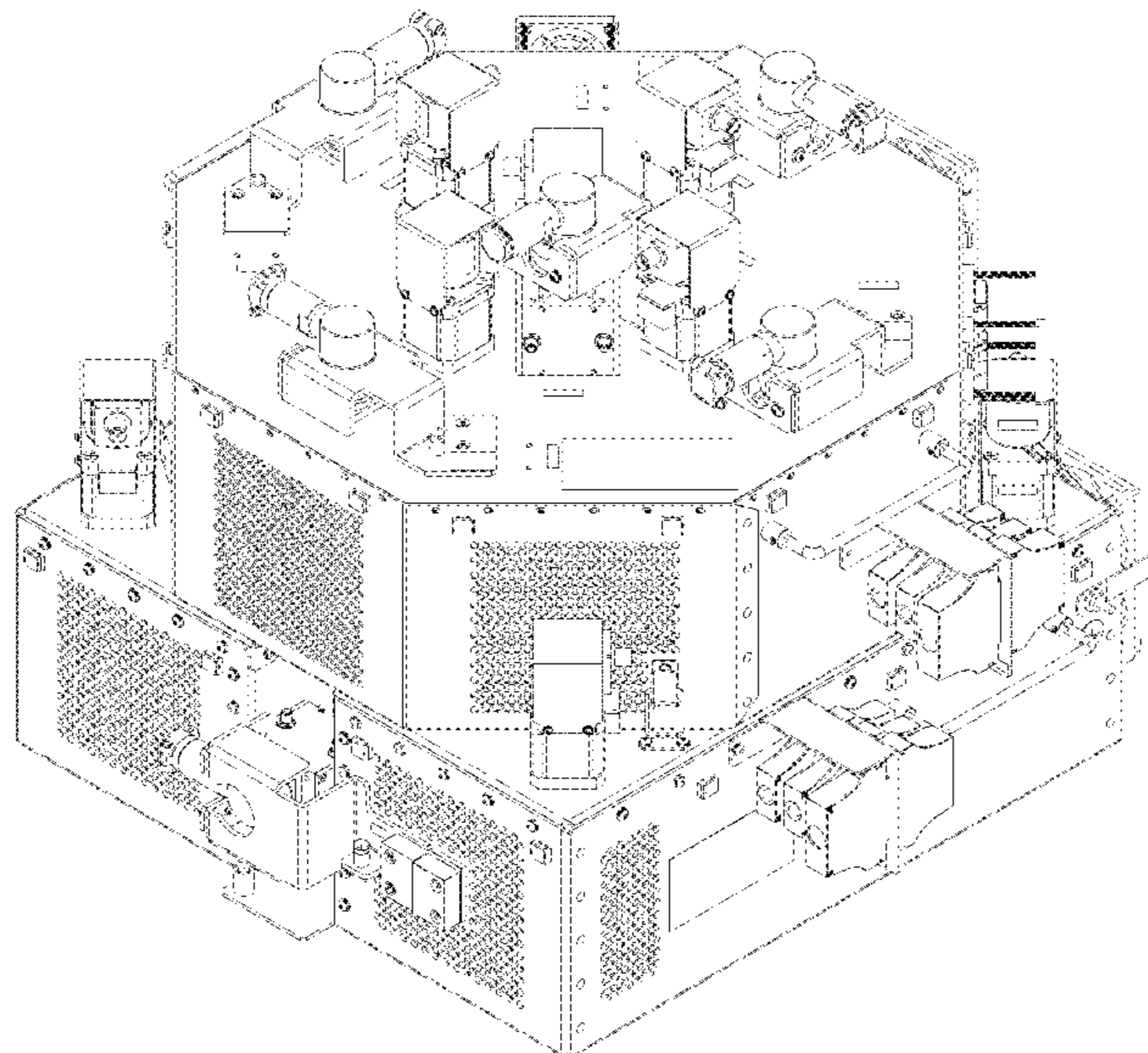
(57) **CLAIM**

The ornamental design for a semiconductor wafer processing tool, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a semiconductor wafer processing tool, showing my new design; FIG. 2 is a front view thereof; FIG. 3 is a rear view thereof; FIG. 4 is a left side view thereof; FIG. 5 is a right side view thereof; FIG. 6 is a top plan view thereof; and, FIG. 7 is a bottom plan view thereof.

**1 Claim, 7 Drawing Sheets**



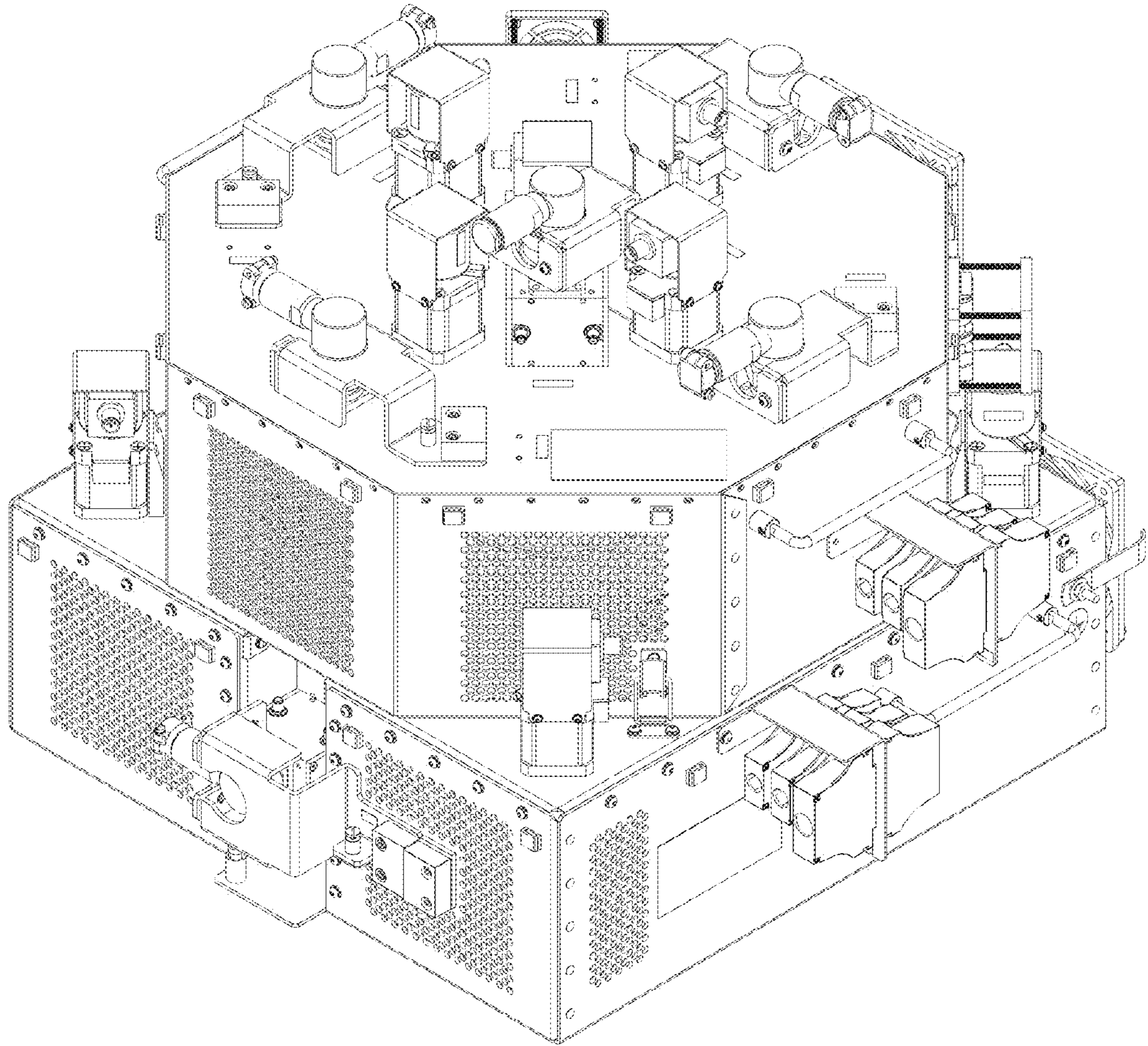


FIG. 1

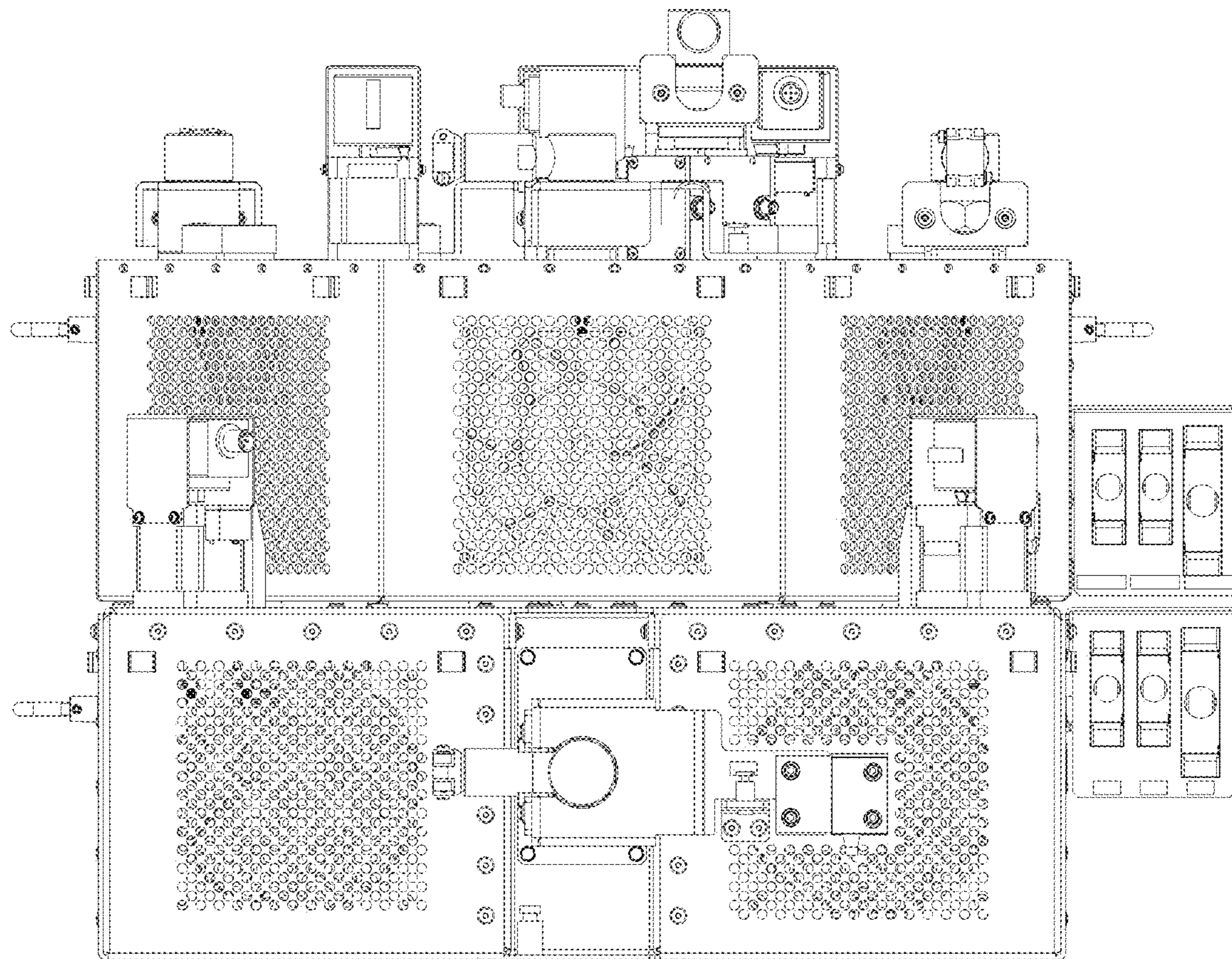


FIG. 2

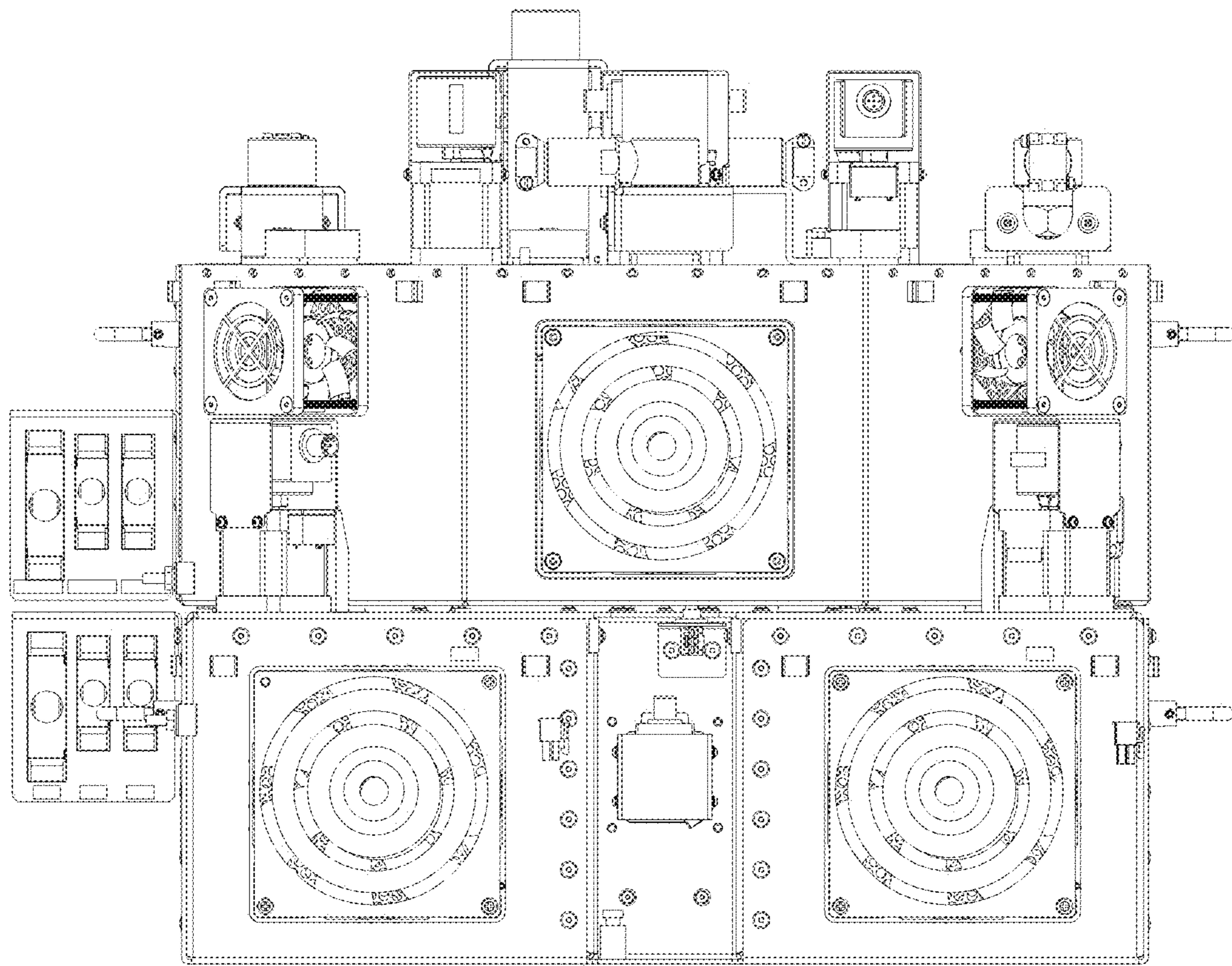


FIG. 3

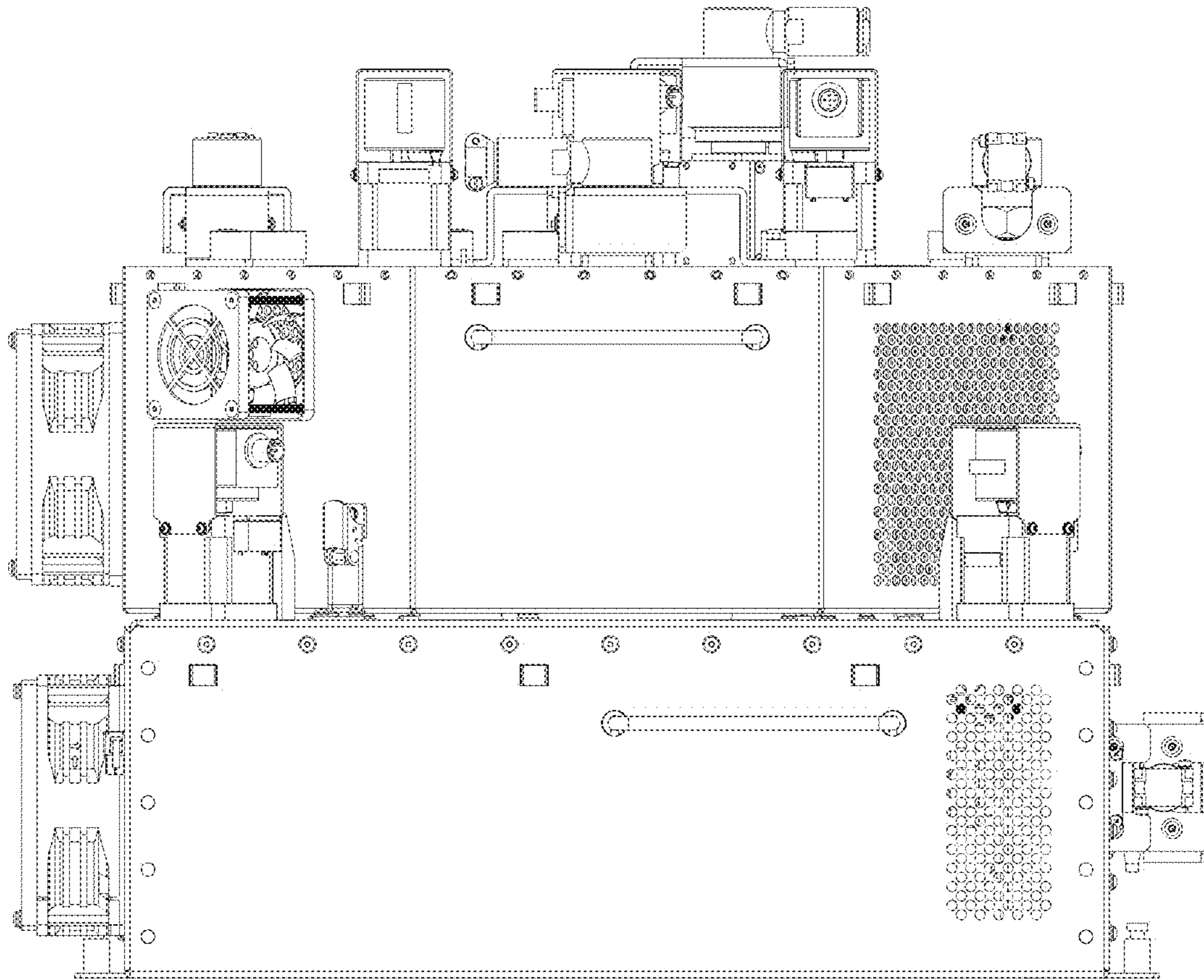


FIG. 4

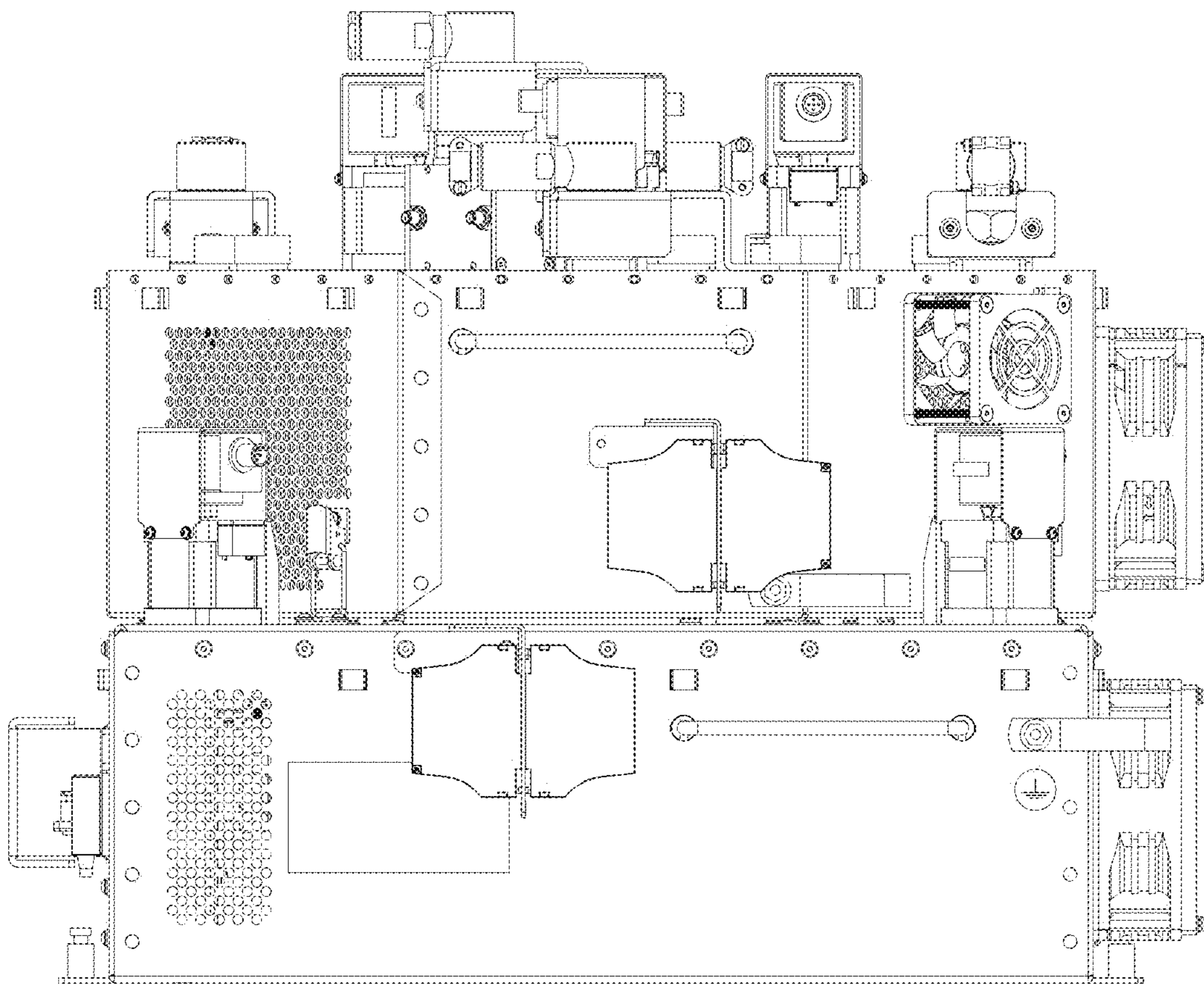


FIG. 5

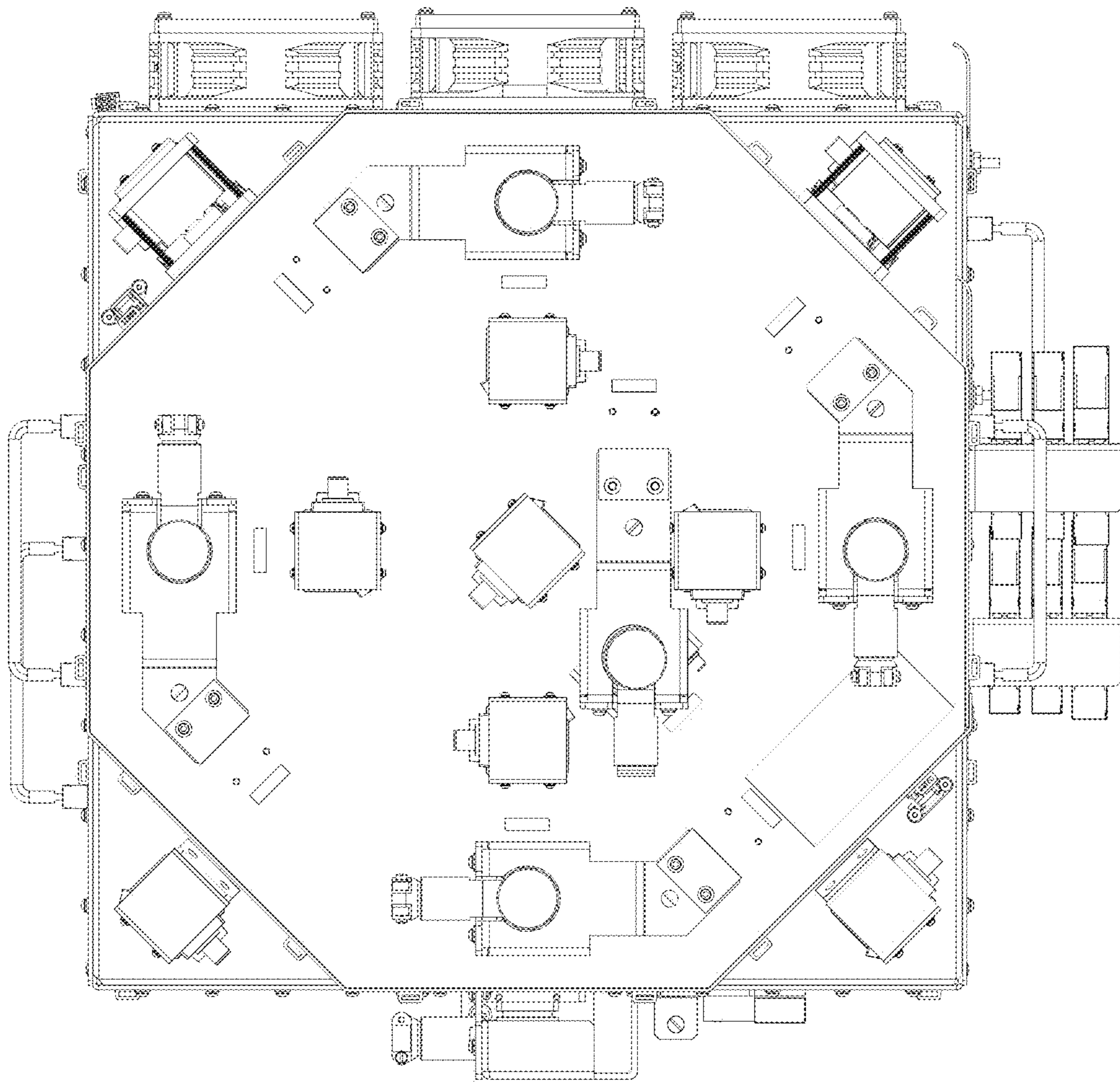


FIG. 6

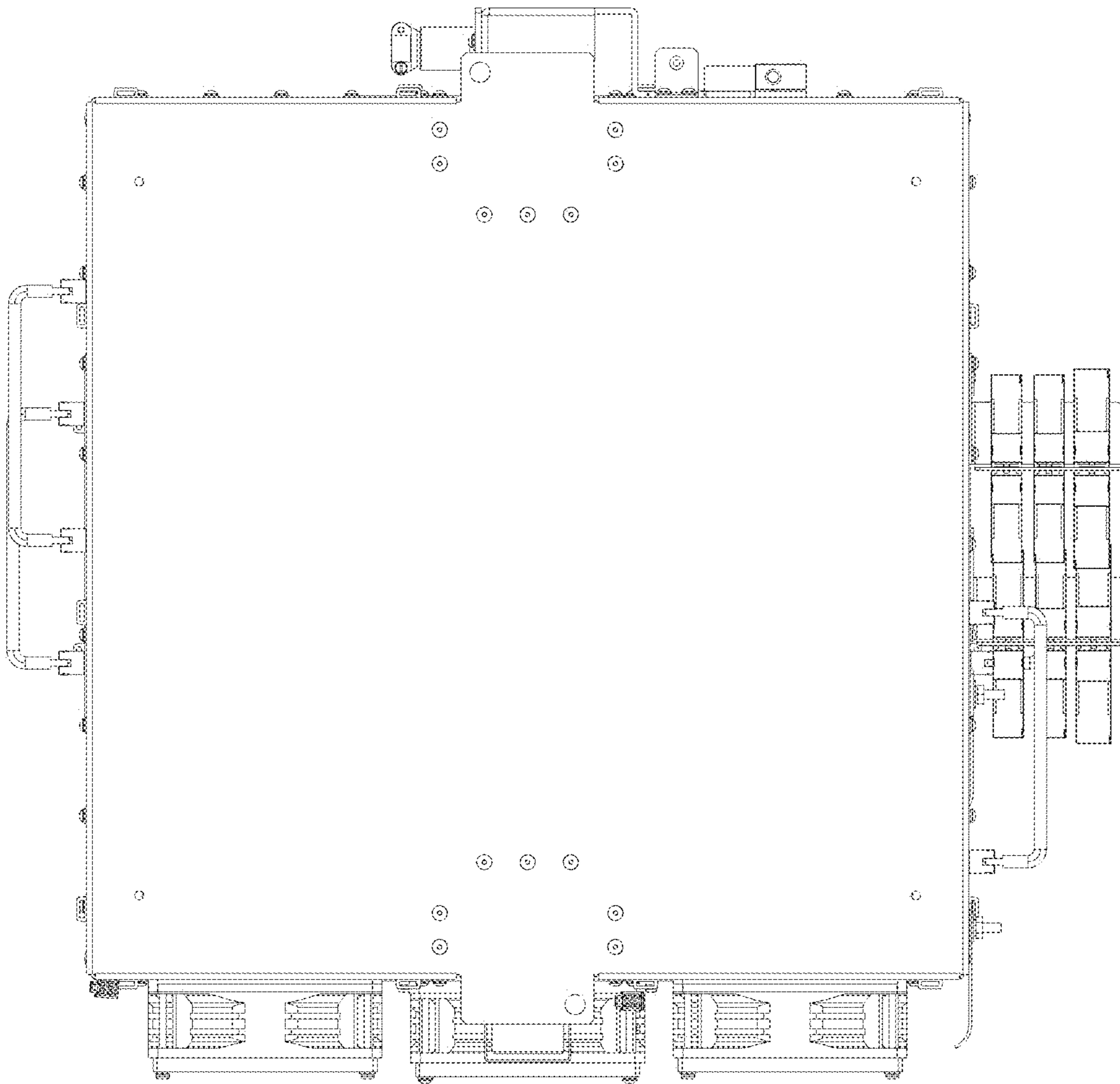


FIG. 7